

layer 34 is provided for redistributing the electrodes of the semiconductor chip 32 to predetermined positions on the redistribution layer 34.--

IN THE CLAIMS:

Please cancel claims 6-12 without prejudice or disclaimer to the subject matter recited therein. Please amend claims 1 and 13 as follows. For the convenience of the Office, all pending claims are listed as shown hereinbelow. Please amend claims 1 and 13 as follows.

1. (Amended) A semiconductor device comprising:
 - a semiconductor element having a plurality of electrodes;
 - a redistribution layer ~~which connects the electrodes of the semiconductor device to electrode pads located in predetermined positions of the redistribution layer~~ having a plurality of electrode pads and conductive patterns connecting the electrodes of the semiconductor element to the respective electrode pads;
 - a plurality of metal posts formed on the electrode pads of the redistribution layer, the metal posts being configured to be provided with external connection electrodes; and
 - at least one mark member which serves as an alignment mark located in a predetermined positional relationship with the metal posts,
- wherein the mark member is made of the same material as the metal posts.

2. The semiconductor device as claimed in claim 1, wherein the alignment mark has an outer configuration other than a circle.

3. The semiconductor device as claimed in claim 1, wherein a width of the alignment mark measured along a plane parallel to a surface of the redistribution layer is greater than a height of the metal posts.

4. A semiconductor device comprising:
a semiconductor element having a plurality of electrodes;
a redistribution layer which connects the electrodes of the semiconductor device to electrode pads located in predetermined positions of the redistribution layer; and
at least one mark member which serves as an alignment mark located in a predetermined positional relationship with the electrode pads, wherein the mark member is made of the same material with the electrode pads.

5. The semiconductor device as claimed in claim 4, wherein the alignment mark has an outer configuration other than a circle.

13. (Amended) An apparatus for fixing a semiconductor wafer by suction, comprising:
a vacuum chuck table having a plurality of concentric suction grooves;

a plurality of suction passages being connected to the plurality of concentric suction grooves, the plurality of concentric suction grooves being divided into a plurality of groups so that each of the plurality of suction passages is connected to one of a corresponding suction grooves belonging to one of the plurality of groups; and

means for sequentially introducing a suctioning force into the suction passages at different timing.